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VIA PFM[™] PFM4914xB6M48D0yzz

Isolated AC-DC Converter with PFC

Features & Benefits

- Universal input (85 to 264 V_{AC})
- 48 V_{OUT}, regulated, isolated •
- 400 W maximum power
- High efficiency ٠
- Built-in EMI filtering •
- Chassis mount or board mount packaging options
- Always-on, self-protecting converter control architecture •
- **SELV** Output
- Two temperature grades including operation to -40°C
- Robust package •
- Versatile thermal management •
- Safe and reliable secondary-side energy storage ٠
- High MTBF •
- 127 W/cubic inch power density
- 4914 package
- External rectification and transient protection required

Typical Applications

- Small cell base stations
- Telecom switching equipment •

Part Ordering Information

- LED lighting
- Test and measurement equipment
- 200 400 W Industrial power systems

Length in

Width in

Inches x 10 Inches x 10

Office equipment

Product Description

The VIA PFM is a highly advanced 400 W AC-DC converter operating from a rectified universal AC input which delivers an isolated and regulated Safety Extra Low Voltage (SELV) 48 V secondary output.

This unique, ultra-low profile module incorporates AC-DC conversion, integrated filtering and transient surge protection in a chassis mount or PCB mount form factor.

The VIA PFM enables a versatile two-sided thermal strategy which greatly simplifies thermal design challenges.

When combined with downstream Vicor DC-DC conversion components and regulators, the VIA PFM allows the Power Design Engineer to employ a simple, low-profile design which will differentiate his end-system without compromising on cost or performance metrics.



Output Max Product Package Package Package Input Range Voltage Output **Product Grade** Function Length Width Туре Voltage Ratio (Range) Current Ρ F 9 4 D 0 Μ 4 1 х В 6 Μ 4 8

00 = Chassis/Always On $C = -20 \text{ to } 100^{\circ}C$ 04 = Short Pin/Always On T = -40 to $100^{\circ}C$ 08 = Long Pin/Always On

У

7

VIA PFM[™] Page 1 of 24

PFM =

Power Factor

Module

Rev 1.3 07/2015

B = Board VIA

V = Chassis VIA

vicorpower.com 800 927.9474

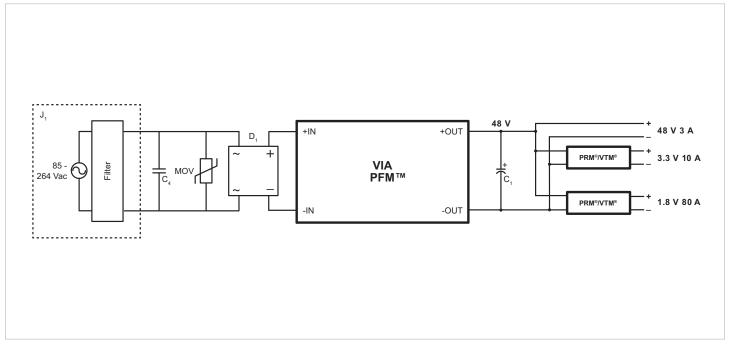
Internal Reference



7

Option Field

Typical PCB Mount Applications

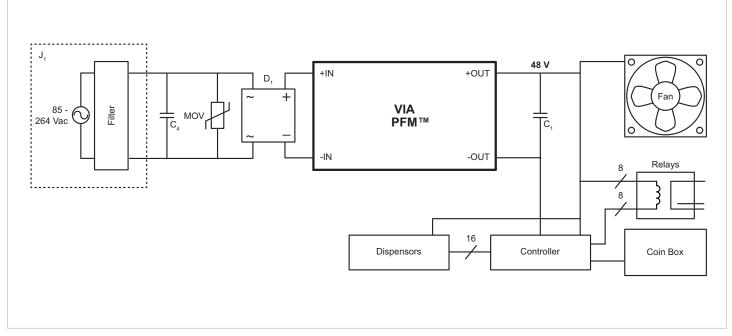


The PCB terminal option allows mounting on an industry standard printed circuit board, with two different pin lengths. Vicor offers a variety of downstream DC-DC converters driven by the 48 V output of the VIA PFM. The 48 V output is usable directly by loads that are tolerant of the PFC line ripple, such as fans, motors, relays, and some types of lighting. Use downstream DC-DC Point of Load converters where more precise regulation is required.

Parts List for Typical PCB Mount Applications					
J1	Delta 06AR2 EMI Filter Entry Module, C14 6 A 250 V 5 x 20 mm fuseholder				
F1 (mount in J1)	Littelfuse 0216008.MXP 8 A 250 VAC 5 x 20 mm holder				
D1	Fairchild GBPC1210W 12 A 1000 V PTH				
C1	Nichicon UVR1J472MRD 4700 μF 63 V 3.4 A 22 x 50 mm bent 90° x 2 pcs or				
	CDE 380LX472M063K022 4700 µF 63 V 4.9 A 30 x 30 mm snap x 2 pcs or				
	Sic Safco Cubisic LP A712121 10,000 μF 63 V 6.4 A 45 x 75 x 12 mm rectangular				
C4	Panasonic ECQ-U2A474ML 0.47 μF 275 V				
MOV	Littelfuse TMOV20RP300E VARISTOR 10 kA 300 V 250 J 20 mm				



Typical Chassis Mount Applications

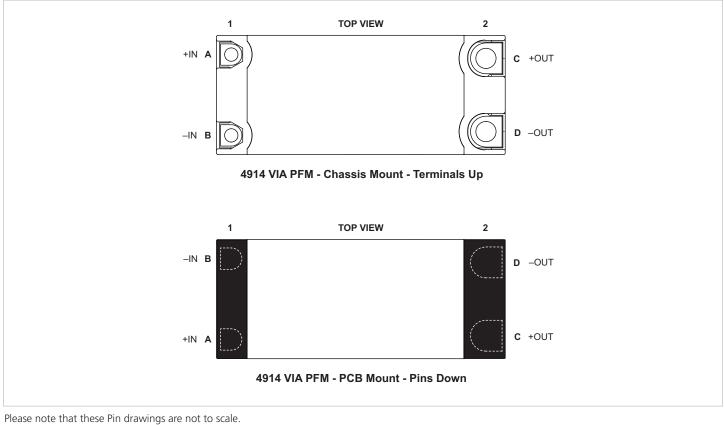


The VIA PFM is available in Chassis Mount option, saving the cost of a PCB and allowing access to both sides of the power supply for cooling. The parts list below minimizes the number of interconnects required between necessary components, and selects components with terminals traditionally used for point to point chassis wiring.

Parts List for Typical Chassis Mount Applications				
J1	Delta 06AR2 EMI Filter Entry Module, C14 6 A 250 V 5 x 20 mm fuseholder			
F1 (mount in J1)	Littelfuse 0216008.MXP 8 A 250 VAC 5 x 20 mm holder			
D1	Fairchild GBPC1210FS 12 A 1000 V 0.25" QC TERMINAL			
C1	UCC E32D630HPN103MA67M 10,000 μF, 63 V 7.4 A, 35 x 67 mm screw terminal or			
	Kemet ALS30A103DE063, 10,000 μF 63 V 10.8 A 36 x 84 mm screw terminal			
C4	Panasonic ECQ-U2A474ML 0.47 μF 275 V			
MOV	Littelfuse TMOV20RP300E VARISTOR 10 kA 300 V 250 J 20 mm			



Pin Configuration



Pin Descriptions

Pin Number	Signal Name	Туре	Function
A1	+IN	INPUT POWER	Positive input power terminal
B1	-IN	INPUT POWER RETURN	Negative input power terminal
C2	+OUT	OUTPUT POWER	Positive output power terminal
D2	-OUT	OUTPUT POWER RETURN	Negative output power terminal

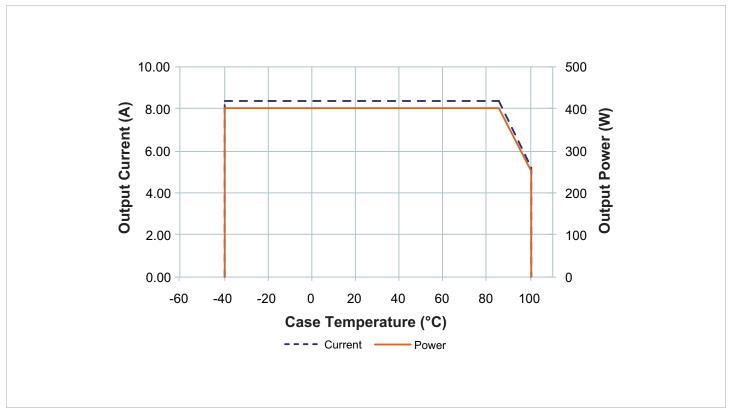


Absolute Maximum Ratings

The absolute maximum ratings below are stress ratings only. Operation at or beyond these maximum ratings can cause permanent damage to the device.

Parameter	Comments	Min	Мах	Unit
Input voltage +IN to –IN	1 ms max	0	600	Vpk
Input voltage (+IN to -IN)	Continuous, Rectified	0	275	V _{RMS}
Output voltage (+Out to -Out)		-0.5	58	V _{DC}
Output current		0.0	12.4	А
Operating junction temperature	T-Grade	-40	125	°C
Storage temperature	T-Grade	-40	125	°C
Dielectric Withstand*	See note below			
Input-Case	Basic Insulation	2121		Vdc
Input-Output	Reinforced Insulation	4242		Vdc
Output-Case	Functional Insulation	707		Vdc

* Please see Dielectric Withstand section. See page 18.



Safe Operating Area



Electrical Specifications

Specifications apply over all line and load conditions, 50 Hz and 60 Hz line frequencies, $T_J = 25^{\circ}$ C, unless otherwise noted. **Boldface** specifications apply over the temperature range of the specified product grade. C_{OUT} is 10,000 µF +/- 20% unless otherwise specified.

Attribute	Symbol	Conditions / Notes	Min	Тур	Max	Uni
		Power Input Specification				
Input voltage range, continuous operation	V _{IN}		85		264	V _{RM}
Input voltage range, transient, non-operational (peak)	V _{IN}	1 ms			600	V
Input voltage cell reconfiguration low-to-high threshold	V _{IN-CR+}			145	148	V _{RM}
Input voltage cell reconfiguration high-to-low threshold	V _{IN-CR-}		132	135		V _{RM}
Input current (peak)	I _{INRP}	See Figure 8, Startup Waveforms			12	А
Source line frequency range	f _{line}		47		63	Hz
Power factor	PF	Input power >200 W		0.96		-
Input inductance, maximum	L _{IN}	Differential mode inductance, common mode inductance may be higher. See section "Source Inductance Considerations" on page 16.			1	mH
Input capacitance, maximum	C _{IN}	After bridge rectifier, between +IN and - IN			1.5	μF
		No Load Specification				
Input power – no load, maximum	P _{NL}				7	W
		Power Output Specification				
Output voltage set point	V _{OUT}	V _{IN} = 230 Vrms, 100% Load	46	48	50	V
Output voltage, no load	V _{OUT-NL}	Over all operating steady state line conditions	42		52	V
Output voltage range (transient)	V _{OUT}	Non-faulting abnormal line and load transient conditions	30		57.6	V
Output power	P _{OUT}	See SOA on Page 4			400	W
		V_{IN} = 230 V, full load, exclusive of input rectifier losses	90.5	92		%
Efficiency	η	$85 \text{ V} < \text{V}_{\text{IN}} < 264 \text{ V}$, full load, exclusive of input rectifier losses	90			%
		$85 \text{ V} < \text{V}_{\text{IN}} < 264 \text{ V}, 75\%$ load, exclusive of input rectifier losses	90			%
Output voltage ripple, switching frequency	V _{OUT-PP-HF}	Over all operating steady-state line and load conditions, 20 MHz BW, measured at C3, Figure 5		200	2000	m∨
Output voltage ripple line frequency	V _{OUT-PP-LF}	Over all operating steady-state line and load conditions, 20 MHz BW		3.0	7.0	V
Output capacitance (external)	C _{OUT-EXT}	Allows for ±20% capacitor tolerance	6800		15000	μF
Output turn-on delay	T _{ON}	From V_{IN} applied		500	1000	ms
Start-up setpoint aquisition time	T _{SS}	Full load		500	1000	ms
Cell reconfiguration response time	T _{CR}	Full load		5.5	11	ms
Voltage deviation (transient)	%V _{OUT-TRANS}		-37.5		20	%
Recovery time	T _{TRANS}			300	600	ms
Line regulation	%V _{OUT-LINE}	Full load			3	%
Load regulation	%V _{OUT-LOAD}	10% to 100% load			3	%
Output current (continuous)	I _{OUT}	SOA			8.33	A
Output current (transient)	I _{OUT-PK}	20 ms duration, average power ≤P _{OUT} , max			12.5	A

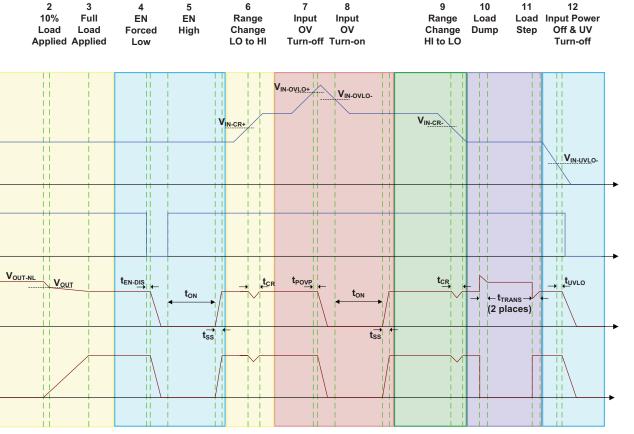
Electrical Specifications (Cont.)

Specifications apply over all line and load conditions, 50 Hz and 60 Hz line frequencies, $T_J = 25$ °C, unless otherwise noted. **Boldface** specifications apply over the temperature range of the specified product grade. C_{OUT} is 10,000 µF +/- 20% unless otherwise specified.

Attribute	Symbol	Conditions / Notes	Min	Тур	Max	Unit
		Powertrain Protections				
Input undervoltage turn-on	V _{IN-ULVO+}	See Timing Diagram		74	83	V _{RMS}
Input undervoltage turn-off	V _{IN-ULVO-}		65	71		V _{RMS}
Input overvoltage turn-on	V _{IN-ULVO-}	See Timing Diagram	265	270		V _{RMS}
Input overvoltage turn-off	V _{IN-ULVO+}			273	287	V _{RMS}
Output overvoltage threshold	V _{OUT-ULVO+}	Instantaneous, latched shutdown	58	61	64	V
Upper start / restart temperature threshold (case)	T _{CASE-OTP-}		100			°C
Overtemperature shutdown threshold (junction)	T _{J-OTP+}			125		°C
Overtemperature shutdown threshold (case)	T _{CASE-OTP+}			110		°C
Overcurrent blanking time	T _{oc}	Based on line frequency	400	460	550	ms
Input overvoltage response time	T _{POVP}			40		ms
Input undervoltage response time	T _{UVLO}	Based on line frequency		200		ms
Output overvoltage response time	T _{SOVP}	Powertrain on		30		ms
Short circuit response time	T _{SC}	Powertrain on, operational state		270		μs
Fault retry delay time	T _{OFF}	See Timing Diagram		10		S
Output power limit	P _{PROT}	50% overload for 20 ms typ allowed	400			W



Timing diagram





07/2015 Rev 1.3 1 Input Power On & UV

Turn-on

 $V_{\text{IN-RMS}}$

EN

VOUT

ILOAD

Input

Output

VIN-UVLO+

ton

≈30V_{RMS}

2

3

4

6

7

8

9

11

Timing diagram (Cont.)

VIN-UVLO-

13 Input Power ON & UV 14 Output OC 17 Toggle EN 16 20 22 15 18 19 21 23 24 OT Fault Line Output Output Output Recycle Output Output Input Fault oc OVP (Output sċ Drop-Out OVP Input SC & Power Turn-on Recovery Fault OVP Fault Power Fault Recovery Recovery Off & UV (Output OVP Recovery) Turn-off Recovery) 1 i i i 1.1 11 1 | | 1 1 1 11 1 1 | | 11 VIN-UVLO+ VIN-UVLO V_{IN-RMS} L L Input 1 1 1 1 i i i EN VOUT-OVLO+ toc toc ↓ t_{on} t_{ON} toN ▶ Vout tor toff+ton tss tsovp toff+ton ≥t_{OFF}+t_{ON} toFF+toN toFF+toN Output LOAD 1.1

Rev 1.3 07/2015



Application Characteristics Typical characteristics at 20°C with 10,000 µF bulk electrolytic capacitor unless otherwise noted.

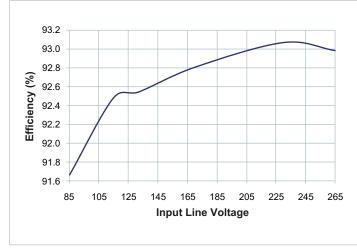


Figure 1 — Full load efficiency vs. line voltage

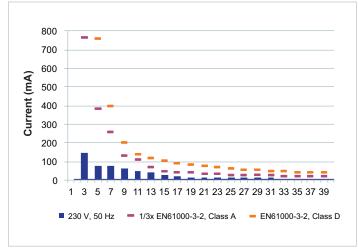


Figure 3 — Typical input current harmonics, full load vs. V_{IN using} typical applications circuit on pages 2 & 3

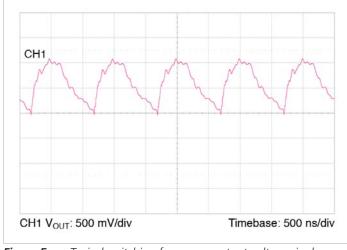
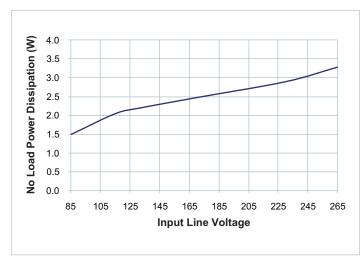


Figure 5 — Typical switching frequency output voltage ripple waveform, $T_{CASE} = 30^{\circ}$ C, $V_{IN} = 230$ V, $I_{OUT} = 8.3$ A, no external ceramic capacitance, 20 MHZ BW





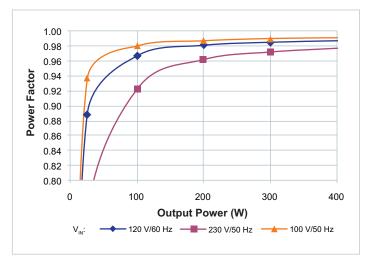


Figure 4 — Typical power factor vs. V_{IN} and I_{OUT} using typical applications circuit on pages 2 & 3

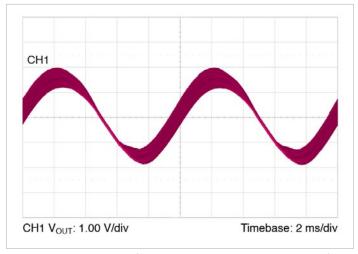
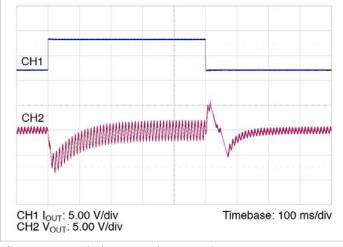
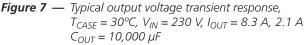


Figure 6 — Typical line frequency output voltage ripple waveform, $T_{CASE} = 30^{\circ}C, V_{IN} = 230 V, I_{OUT} = 8.3 A,$ $C_{OUT} = 10,000 \mu F. 20 MHZ BW$



Application Characteristics (Cont.) Typical characteristics at 20°C with 10,000 µF bulk electrolytic capacitor unless otherwise noted.





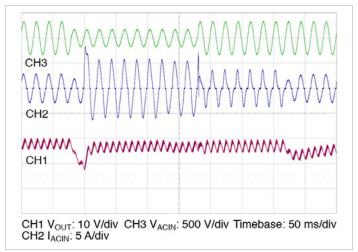


Figure 9 — 230 V, 120 V range change transient response 16.7 A, $I_{OUT} = 8.3 \text{ A}, C_{OUT} = 10,000 \, \mu\text{F}$

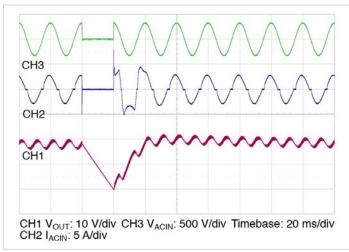
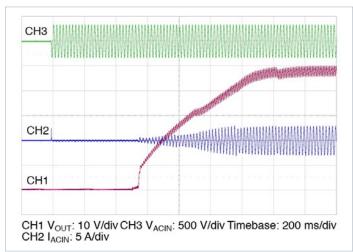
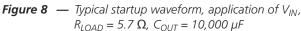
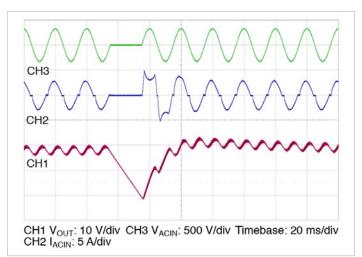
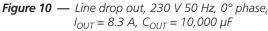


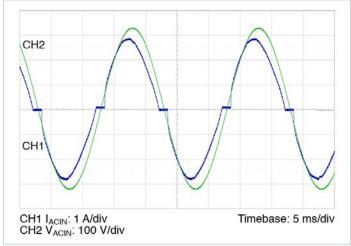
Figure 11 — Line drop out, 230 V50 Hz, 90° phase, $V_{IN} = 230$ V, 50 Hz, $I_{OUT} = 8.3$ A, $C_{OUT} = 10,000 \ \mu F$

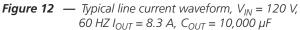














Application Characteristics (Cont.) Typical characteristics at 20°C with 10,000 µF bulk electrolytic capacitor unless otherwise noted.

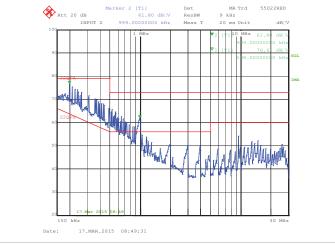


Figure 13 — Typical EMI Spectrum, Peak Scan, 90% load, 115 V_{IN} , $C_{OUT} = 10,000 \ \mu$ F, No Inlet Filter, C4

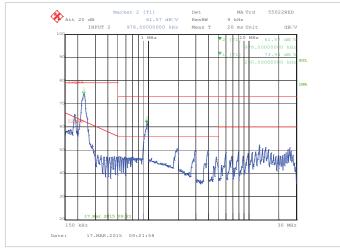
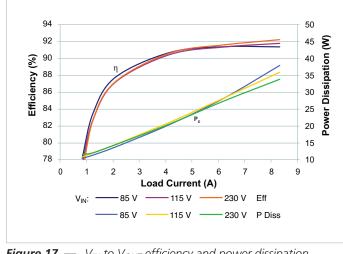
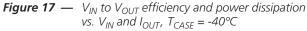


Figure 15 — Typical EMI Spectrum, Peak Scan, 90% load, 230 V_{IN} , $C_{OUT} = 10,000 \ \mu$ F, No Inlet Filter, C4





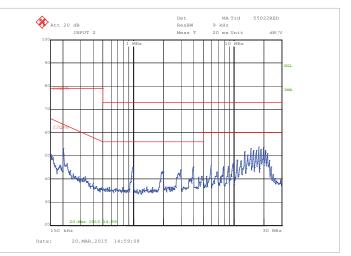


Figure 14 — Typical EMI Spectrum, Peak Scan, 90% load, 115 V_{IN}, C_{OUT} = 10,000 μF using Typical Chassis Mount Application Circuit

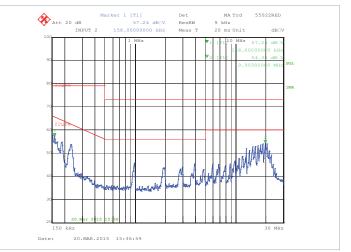


Figure 16 — Typical EMI Spectrum, Peak Scan, 90% load, 230 V_{IN} , $C_{OUT} = 10,000 \ \mu F$ using Typical Chassis Mount Application Circuit

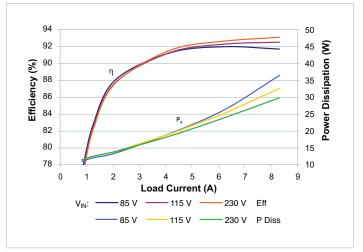


Figure 18 — V_{IN} to V_{OUT} efficiency and power dissipation vs. V_{IN} and I_{OUT} , $T_{CASE} = 20^{\circ}C$



Application Characteristics (Cont.) Typical characteristics at 20°C with 10,000 µF bulk electrolytic capacitor unless otherwise noted.

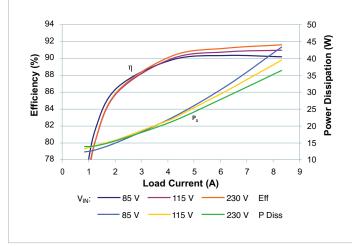


Figure 19 — V_{IN} to V_{OUT} efficiency and power dissipation vs. V_{IN} and I_{OUT} , $T_{CASE} = 85^{\circ}C$



General Characteristics

Specifications apply over all line and load conditions, 50 Hz and 60 Hz line frequencies, TC = 25°C, unless otherwise noted. **Boldface specifications apply over the temperature range of the specified Product Grade.**

Attribute	Symbol	Conditions / Notes	Min	Тур	Max	Unit
		Mechanical				
Length	L			124.8/[4.91]		mm / [in]
Width	W			35.5 / [1.40]		mm / [in]
Height	Н			9.3 / [0.37]		mm / [in]
Volume	Vol	Without heatsink		42.0 / [2.56]		cm ³ / [in ³]
Weight	W			156 / [5.5]		g / [oz]
Pin material		C145 copper, half hard				
Underplate		Low stress ductile nickel	50		100	µin
		Palladium	0.8		6	μin
Pin finish		Soft Gold	0.12		2	µin
	1	Thermal				
Or and in a second second second	Ŧ	C - Grade, see derating curve in SOA	-20		100	°C
Operating case temperature	T _C	T - Grade, see derating curve in SOA	-40		100	°C
Thermal resistance, junction to case, top	R _{JC_TOP}			1.04		°C/W
Thermal resistance, junction to case, bottom	R _{JC_BOT}			1.83		°C/W
Coupling thermal resistance, top to bottom of case, internal	R _{HOU}			0.15		°C/W
Shell Thermal capacity				32		J/K
Thermal design		See Thermal Design on Page 17				
		Assembly				
	ESD _{HBM}	Human Body Model, JEDEC JESD 22-A114C.01	1,000			
ESD rating	ESD _{MM}	Machine Model, JEDEC JESD 22-A115B	N/A			V
	ESD _{CDM}	Charged Device Model, JEDEC JESD 22-C101D	200			
		Safety				
		cTÜVus; EN 60950-1				
Agency approvals/standards		cURus; UL 60950-1				
		CE Marked for Low Voltage Directive and	RoHS Recast D	Directive, as applica	able	
		Touch Current measured in accordance with IEC 60990 using measuring network Figure 3 (VIA PFM only)		0.5		mA
		EMI/EMC Compliance				
FCC Part 15, EN55022, CISPR22: 2006 + A1: 2007, Conducted Emissions		Class B Limits - with –OUT connected to GND				
EN61000-3-2: 2009, Harmonic Current Emissions		Class A				



General Characteristics (Cont.)

Specifications apply over all line and load conditions, 50 Hz and 60 Hz line frequencies, TC = 25°C, unless otherwise noted. **Boldface specifications apply over the temperature range of the specified Product Grade.**

Attribute	Symbol	Conditions / Notes	Min	Тур	Мах	Unit
		EMI/EMC Compliance (cont.)				
EN61000-3-3: 2005, Voltage Changes & Flicker		P _{ST} <1.0; P _{LT} <0.65; dc <3.3% dmax <6%				
EN61000-4-4: 2004, Electrical Fast Transients		Level 2, Performance Criteria A				
EN61000-4-5: 2006, Surge Immunity		Level 3, Immunity Criteria A, external TMOV required				
EN61000-4-6: 2009, Conducted RF Immunity		Level 2, 130 dBµV (3.0 V_{RMS})				
EN61000-4-8: 1993 + A1 2001, Power Frequency H-Field 10A/m, continuous field		Level 3, Performance Criteria A				
EN61000-4-11: 2004, Voltage Dips & Interrupts		Class 2, Performance Criteria A Dips, Performance Criteria B Interrupts				



Product Details and Design Guidelines

Building Blocks and System Designs

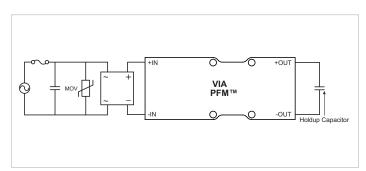


Figure 20 – 400 W Universal AC-to-DC Supply

The VIA PFM is a high efficiency AC-to-DC converter, operating from a universal AC input to generate an isolated SELV 48 VDC output bus with power factor correction. It is the key component of an AC-to-DC power supply system such as the one shown in Figure 20 above.

The input to the VIA PFM is a rectified sinusoidal AC source with a power factor maintained by the module with harmonics conforming to IEC 61000-3-2. Internal filtering enables compliance with the standards relevant to the application (Surge, EMI, etc.). See EMI/EMC Compliance standards on Page 13.

The module uses secondary-side energy storage (at the SELV 48 V bus) to maintain output hold up through line dropouts and brownouts. Downstream regulators also provide tighter voltage regulation, if required.

Traditional PFC Topology

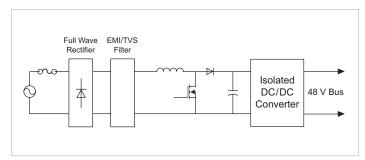


Figure 21 – Traditional PFC AC-to-DC supply

To cope with input voltages across worldwide AC mains (85 – 264 Vac), traditional AC-DC power supplies (Figure 21) use two power conversion stages: 1) a PFC boost stage to step up from a rectified input as low as 85 Vac to ~380 Vdc; and 2) a DC-DC down converter from 380 Vdc to a 48 V bus.

The efficiency of the boost stage and of traditional power supplies is significantly compromised operating from worldwide AC lines as low as 85 Vac.

Adaptive Cell[™] Topology

With its single stage Adaptive Cell™ topology, the VIA PFM enables consistently high efficiency conversion from worldwide AC mains to a 48 V bus and efficient secondary-side power distribution.

Input Fuse Selection

VI Brick products are not internally fused in order to provide flexibility in configuring power systems. Input line fusing is recommended at system level, in order to provide thermal protection in case of catastrophic failure. The fuse shall be selected by closely matching system requirements with the following characteristics:

- Recommended fuse: Change to 216 Series Littlefuse 8A or lower current rating (usually greater than the VIA PFM maximum current at lowest input voltage)
- Maximum voltage rating (usually greater than the maximum possible input voltage)
- Ambient temperature
- Breaking capacity per application requirements
- Nominal melting I2t

Source Inductance Considerations

The VIA PFM Powertrain uses a unique Adaptive Cell Topology that dynamically matches the powertrain architecture to the AC line voltage. In addition the VIA PFM uses a unique control algorithm to reduce the AC line harmonics yet still achieve rapid response to dynamic load conditions presented to it at the DC output terminals. Given these unique power processing features, the VIA PFM can expose deficiencies in the AC line source impedance that may result in unstable operation if ignored.

It is recommended that for a single VIA PFM, the line source inductance should be no greater than 1 mH for a universal AC input of 100 - 240 V. If the VIA PFM will be operated at 240 V nominal only , the source impedance may be increased to 2 mH. For either of the preceding operating conditions it is best to be conservative and stay below the maximum source inductance values. When multiple VIA PFM's are used on a single AC line, the inductance should be no greater than 1 mH/N, where N is the number of VIA PFM's on the AC branch circuit, or 2 mH/N for 240 Vac operation. It is important to consider all potential sources of series inductance including and not limited to, AC power distribution transformers, structure wiring inductance, AC line reactors, and additional line filters. Non-linear behavior of power distribution devices ahead of the VIA PFM may further reduce the maximum inductance and require testing to ensure optimal performance.

If the VIA PFM is to be utilized in large arrays, the VIA PFMs should be spread across multiple phases or sources thereby minimizing the source inductance requirements, or be operated at a line voltage close to 240 Vac. Vicor Applications should be contacted to assist in the review of the application when multiple devices are to be used in arrays.

Fault Handling

Input Undervoltage (UV) Fault Protection

The input voltage is monitored by the micro-controller to detect an input under voltage condition. When the input voltage is less than the $V_{IN-UVLO-}$, a fault is detected, the fault latch and reset logic disables the modulator, the modulator stops powertrain switching, and the output voltage of the unit falls. After a time t_{UVLO} , the unit shuts down. Faults lasting less than t_{UVLO} may not be detected. Such a fault does not go through an auto-restart cycle. Once the input voltage rises above $V_{IN-UVLO+}$, the unit recovers from the input UV fault, the powertrain resumes normal switching after a time t_{ON} and the output voltage of the unit reaches the set-point voltage within a time t_{SS} .



Overcurrent (OC) Fault Protection

The unit's output current, determined by V_{EAO} , V_{IN_B} and the primaryside sensed output voltage is monitored by the microcontroller to detect an output OC condition. If the output current exceeds its current limit, a fault is detected, the reset logic disables the modulator, the modulator stops powertrain switching, and the output voltage of the module falls after a time t_{OC} . As long as the fault persists, the module goes through an auto-restart cycle with off time equal to $t_{OFF} + t_{ON}$ and on time equal to t_{OC} . Faults shorter than a time t_{OC} may not be detected. Once the fault is cleared, the module follows its normal start up sequence after a time t_{OFF} .

Short Circuit (SC) Fault Protection

The microcontroller determines a short circuit on the output of the unit by measuring its primary sensed output voltage and EAO. Most commonly, a drop in the primary-sensed output voltage triggers a short circuit event. The module responds to a short circuit event within a time t_{SC} . The module then goes through an auto restart cycle, with an off time equal to $t_{OFF} + t_{ON}$ and an on time equal to t_{SC} , for as long as the short circuit fault condition persists. Once the fault is cleared, the unit follows its normal start up sequence after a time t_{OFF} . Faults shorter than a time t_{SC} may not be detected.

Temperature Fault Protection

The microcontroller monitors the temperature within the VIA PFM. If this temperature exceeds $T_{I-OTP+r}$

an overtemperature fault is detected, the reset logic block disables the modulator, the modulator stops the powertrain switching and the output voltage of the VIA PFM falls. Once the case temperature falls below $T_{CASE-OTP-}$, after a time greater than or equal to t_{OFF} , the converter recovers and undergoes a normal restart. For the C-grade version of the converter, this temperature is 75°C. Faults shorter than a time t_{OTP} may not be detected. If the temperature falls below $T_{CASE-UTP-}$, an undertemperature fault is detected, the reset logic disables the modulator, the modulator stops powertrain switching and the output voltage of the unit falls. Once the case temperature rises above $T_{CASE-UTP-}$, after a time greater than or equal to t_{OFF} , the unit recovers and undergoes a normal restart.

Output Overvoltage Protection (OVP)

The microcontroller monitors the primary sensed output voltage to detect output OVP. If the primary sensed output voltage exceeds $V_{OUT-OVLO+}$, a fault is latched, the logic disables the modulator, the modulator stops powertrain switching, and the output voltage of the module falls after a time t_{SOVP} . Faults shorter than a time t_{SOVP} may not be detected. This type of fault is a latched fault and requires that 1) the EN pin be toggled or 2) the input power be recycled to recover from the fault.

Hold-up Capacitance

The VIA PFM uses secondary-side energy storage (at the SELV 48 V bus) and optional PRM® regulators to maintain output hold up through line dropouts and brownouts. The module's output bulk capacitance can be sized to achieve the required hold up functionality.

Hold-up time depends upon the output power drawn from the VIA PFM based AC-to-DC front end and the input voltage range of downstream DC-to-DC converters.

The following formula can be used to calculate hold-up capacitance for a system comprised of VIA PFM and a downstream regulator:

Output Filtering

The VIA PFM requires an output bulk capacitor in the range of 6,800 μF

$$C = 2*P_{OUT}*(0.005+t_d)/(V_2^2 - V_1^2)$$

where:

С	VIA PFM's output bulk capacitance in farads
t _d	Hold-up time in seconds
P _{OUT}	VIA PFM's output power in watts
V_2	Output voltage of VIA PFM's

converter in volts

*V*₁ *Downstream regulator undervoltage turn off (volts)*

-OR-

 P_{OUT}/I_{OUT-PK} , whichever is greater.

to 15,000 μ F for proper operation of the PFC front-end. A minimum 10,000 μ F is recommended for full rated output. Capacitance can be reduced proportionally for lower maximum loads.

The output voltage has the following two components of voltage ripple:

1) Line frequency voltage ripple: $2{\star}f_{\text{LINE}}$ Hz component

2) Switching frequency voltage ripple: 1 MHz module switching frequency component (see Figure 5).

Line Frequency Filtering

Output line frequency ripple depends upon output bulk capacitance. Output bulk capacitor values should be calculated based on line frequency voltage ripple. High-grade electrolytic capacitors with adequate ripple current ratings, low ESR and a minimum voltage rating of 63 V are recommended.

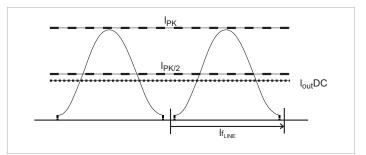


Figure 22 – Output current waveform



Based on the output current waveform, as seen in Figure 22, the following formula can be used to determine peak-to-peak line frequency output voltage ripple:

$$V_{PPl} \cong 0.2 * P_{OUT} / (V_{OUT} * f_{LINE} * C)$$

where:

$V_{PP}l$	Output voltage ripple Peak-to-peak line frequency
P_{OUT}	Average output power
V_{OUT}	Output voltage set point, nominally 48 V
f_{LINE}	Frequency of line voltage
С	Output bulk capacitance
I _{DC}	Maximum average output current
IPK	Peak-to-peak line frequency output current ripple

In certain applications, the choice of bulk capacitance may be determined by hold-up requirements and low frequency output voltage filtering requirements. Such applications may use the greater capacitance value determined from these requirements. The ripple current rating for the bulk capacitors can be determined from the following equation:

$$I_{ripple} = 0.8 * P_{OUT} / V_{OUT}$$

Switching Frequency Filtering

This is included within the VIA PFM. No external filtering is necessary for most applications. For the most noise sensitive applications, a common mode choke followed by two caps to PE GND will reduce switching noise further.

EMI Filtering and Transient Voltage Suppression EMI Filtering

The VIA PFM with PFC is designed such that it will comply with EN55022 Class B for Conducted Emissions with a commercially available off-the-shelf EM filter. The emissions spectrum is shown in Figures 13 - 16. If one of the outputs is connected to earth ground, a small output common mode choke is also recommended.

EMI performance is subject to a wide variety of external influences such as PCB construction, circuit layout etc. As such, external components in addition to those listed herein may be required in specific instances to gain full compliance to the standards specified.

Transient Voltage Suppression

The VIA PFM contains line transient suppression circuitry to meet specifications for surge (i.e. EN61000-4-5) and fast transient conditions (i.e. EN61000-4-4 fast transient/"burst").

Thermal Considerations

The VIA[™] package provides effective conduction cooling from either of the two module surfaces. Heat may be removed from the top surface, the bottom surface or both. The extent to which these two surfaces are cooled is a key component for determining the maximum power that can be processed by a VIA, as can be seen from specified thermal operating area on Page 4. Since the VIA has a maximum internal temperature rating, it is necessary to estimate this internal temperature based on a system-level thermal solution. To this purpose, it is helpful to simplify the thermal solution into a roughly equivalent circuit where power dissipation is modeled as a current source, isothermal surface temperatures are represented as voltage sources and the thermal resistances are represented as resistors. Figure 23 shows the "thermal circuit" for the VIA module.

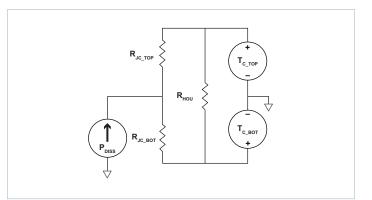


Figure 23 – Double sided cooling VIA thermal model

In this case, the internal power dissipation is P_{DISS} , R_{JC_TOP} and R_{JC_BOT} are thermal resistance characteristics of the VIA module and the top and bottom surface temperatures are represented as T_{C_TOP} , and T_{C_BOT} . It interesting to notice that the package itself provides a high degree of thermal coupling between the top and bottom case surfaces (represented in the model by the resistor R_{HOU}). This feature enables two main options regarding thermal designs:

Single side cooling: the model of Figure 23 can be simplified by calculating the parallel resistor network and using one simple thermal resistance number and the internal power dissipation curves; an example for bottom side cooling only is shown in Figure 24.

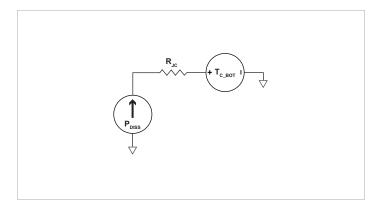


Figure 24 – Single-sided cooling VIA thermal model

In this case, RJC can be derived as following:

$$R_{JC} = \frac{(R_{JC_TOP} + R_{HOU}) \bullet R_{JC_BOT}}{R_{JC_TOP} + R_{HOU} + R_{JC_BOT}}$$



Double side cooling: while this option might bring limited advantage to the module internal components (given the surfaceto-surface coupling provided), it might be appealing in cases where the external thermal system requires allocating power to two different elements, like for example heatsinks with independent airflows or a combination of chassis/air cooling.

Powering a Constant Power Load

When the output voltage of the VIA PFM module is applied to the input of the downstream regulator, the regulator turns on and acts as a constant-power load. When the module's output voltage reaches the input undervoltage turn on of the regulator, the regulator will attempt to start. However, the current demand of the downstream regulator at the undervoltage turn-on point and the hold-up capacitor charging current may force the VIA PFM into current limit. In this case, the unit may shut down and restart repeatedly. In order to prevent this multiple restart scenario, it is necessary to delay enabling a constant-power load when powered up by the upstream VIA PFM until after the output set point of the VIA PFM is reached.

This can be achieved by

- **1.** keeping the downstream constant-power load off during power up sequence
 - and
- 2. turning the downstream constant-power load on after the output voltage of the module reaches 48 V steady state

After the initial startup, the output of the VIA PFM can be allowed to fall to 30 V during a line dropout at full load. In this case, the circuit should not disable the downstream regulator if the input voltage falls after it is turned on; therefore, some form of hysteresis or latching is needed on the enable signal for the constant power load. The output capacitance of the VIA PFM should also be sized appropriately for a constant power load to prevent collapse of the output voltage of the module during line dropout (see Hold up Capacitance on Page 17). A constant-power load can be turned off after completion of the required hold up time during the power-down sequence or can be allowed to turn off when it reaches its own undervoltage shutdown point.

The timing diagram in Figure 25 shows the output voltage of the VIA PFM and the downstream regulator's enable pin voltage and output voltage of the PRM regulator for the power up and power down sequence. It is recommended to keep the time delay approximately 10 to 20 ms.

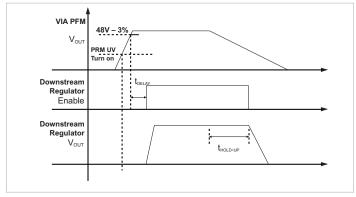


Figure 25 – PRM Enable Hold off Waveforms

Special care should be taken when enabling the constant-power load near the auto-ranger threshold, especially with an inductive source upstream of the VIA PFM. A load current spike may cause a large input voltage transient, resulting in a range change which could temporarily reduce the available power (see Adaptive Cell[™] Topology below).

Adaptive Cell[™] Topology

The Adaptive Cell topology utilizes magnetically coupled "top" and "bottom" primary cells that are adaptively configured in series or parallel by a configuration controller comprised of an array of switches. A microcontroller monitors operating conditions and defines the configuration of the top and bottom cells through a range control signal.

A comparator inside the microcontroller monitors the line voltage and compares it to an internal voltage reference.

If the input voltage of the VIA PFM crosses above the positive going cell reconfiguration threshold voltage, the top cell and bottom cell configure in series and the unit operates in "high" range.

If the peak of input voltage of the unit falls below the negative-going range threshold voltage for two line cycles, the cell configuration controller configures the top cell and bottom cell in parallel, the unit operates in "low" range.

Power processing is held off while transitioning between ranges and the output voltage of the unit may temporarily droop. External output hold up capacitance should be sized to support power delivery to the load during cell reconfiguration. The minimum specified external output capacitance is sufficient to provide adequate ride-through during cell reconfiguration for typical applications. Waveforms showing active cell reconfiguration can be seen in Figure 9.

Dielectric Withstand

The chassis of the VIA PFM is required to be connected to Protective Earth when installed in the end application and must satisfy the requirements of IEC 60950-1 for Class I products. Both sides of the housing are required to be connected to Protective Earth to satisfy safety and EMI requirements. Protective earthing can be accomplished through dedicated wiring harness (example: ring terminal clamped by mounting screw) or surface contact (example: pressure contact on bare conductive chassis or PCB copper layer with no solder mask).

The VIA PFM contains an internal safety approved isolating component (VI ChiP) that provides the Reinforced Insulation from Input to Output. The isolating component is individually tested for Reinforced Insulation from Input to Output at 3000 Vac or 4242 Vdc prior to the final assembly of the VIA[™].

When the VIA assembly is complete the Reinforced Insulation can only be tested at Basic Insulation values as specified in the electric strength Test Procedure noted in clause 5.2.2 of IEC 60950-1.

Test Procedure Note from IEC 60950-1

vicorpower.com

800 927.9474

"For equipment incorporating both REINFORCED INSULATION and lower grades of insulation, care is taken that the voltage applied to the REINFORCED INSULATION does not overstress BASIC INSULATION or SUPPLEMENTARY INSULATION."



Summary

The final VIA assembly contains basic insulation from input to case, reinforced insulation from input to output, and functional insulation from output to case.

The output of the VIA complies with the requirements of SELV circuits so only functional insulation is required from the output (SELV) to case (PE) because the case is required to be connected to protective earth in the final installation. The construction of the VIA can be summarized by describing it as a "Class II" component installed in a "Class I" subassembly. The reinforced insulation from input to output can only be tested at a basic insulation value of 2121 Vdc on the completely assembled VIA product.

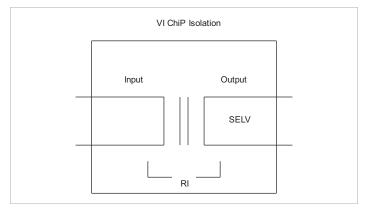


Figure 26 – VI Chip before final assembly in the VIA

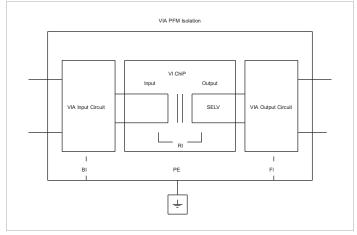
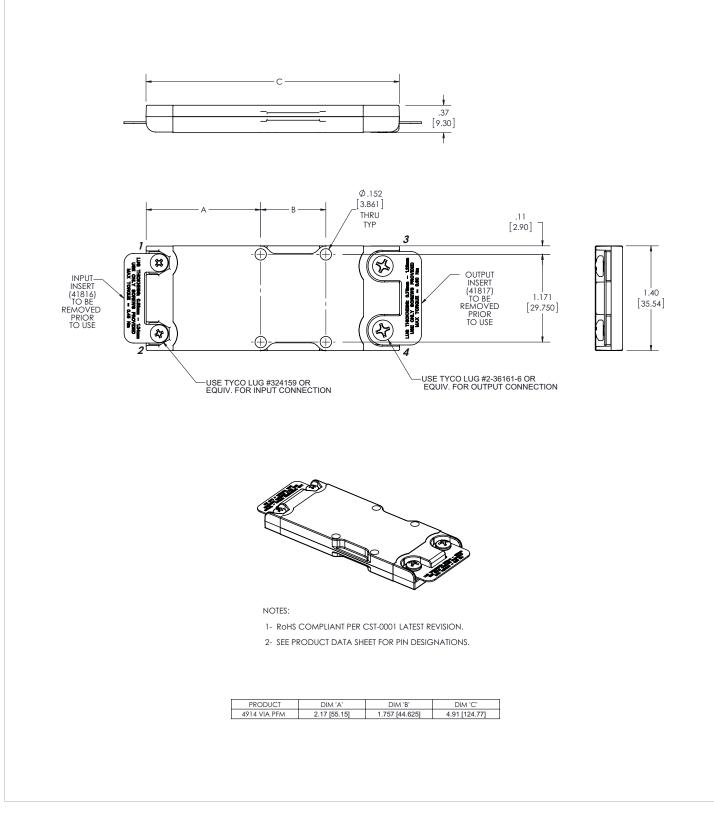


Figure 27 – PFM VIA after final assembly



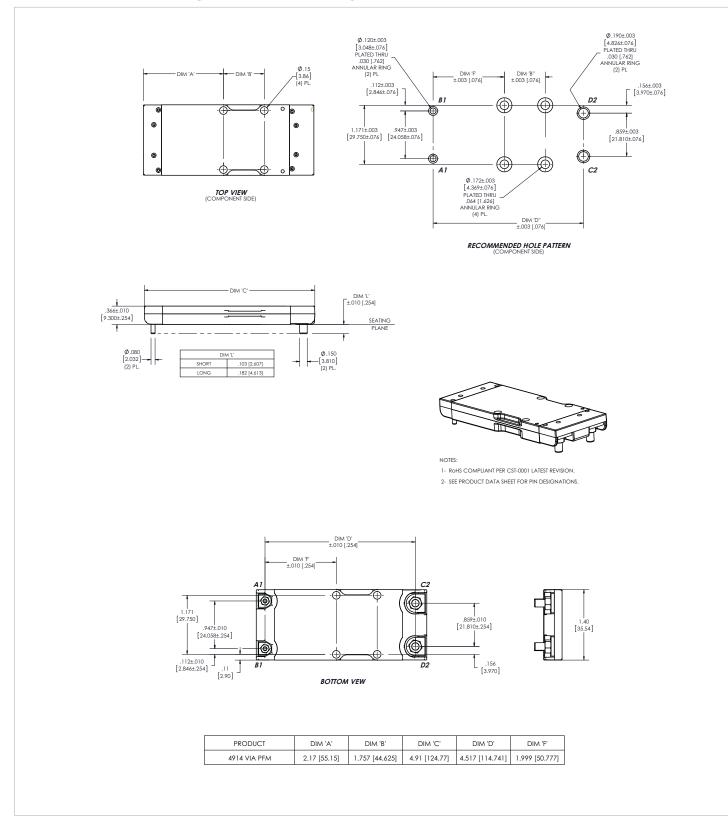
VIA PFM Chassis Mount Package Mechanical Drawing



Product outline drawing; Product outline drawings are available in .pdf and .dxf formats. 3D mechanical models are available in .pdf and .step formats.



VIA PFM PCB Mount Package Mechanical Drawing and Recommended Land Pattern





Revision History

Revision	Date	Description	Page Number(s)
1.0	05/15/15	Intital release	n/a
1.1	05/15	Mechanical Drawing change	20
1.2	06/10/15	Revised typical application part numbers SOA Voltage changes Grounding note added Pin name change	2, 3 4 16 18 20
1.3	07/16/15	Added Pin Configuration and Description page Added Source Inductor Consideration note Added Safety Approvals Added Source Inductor Consideration section Updated Mechanical drawing	4 6 14 16 21



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